

## IN THE CLAIMS

Kindly amend claims 1, 2, 3 and 5 as shown in the following claim listing:

1. (currently amended) A photolithographic process comprising the steps of:

- applying a photoresist layer (2), with a substantially uniform thickness, on a substrate (1),
- locally exposing the photoresist layer (2) to a radiation source with a suitable wavelength,
- providing a suitable liquid developer composition on the substrate (1),
- dissolving an exposed or unexposed region of the photoresist layer (2) with the developer composition, and
- rinsing and drying the photoresist layer (2) thereby interrupting said dissolving step,

wherein the substrate (1) has a metallic surface (1c) in contact with the photoresist layer (2) and the photoresist layer (2) has a thickness  $d_r < 100\text{nm}$  to improve photoresist wall steepness.

2. (currently amended) A photolithographic process as claimed in claim 1, wherein the substrate comprises a metallic surface layer (1b), with a thickness  $d_m$  larger than approximately 10nm, and

a further substrate material (1a).

3. (currently amended) A photolithographic process a as claimed in claim 1, wherein the metallic surface (1c) comprises the chemical elements Ni, Cr or Au.

4. (previously presented) A photolithographic process as claimed in claim 1, wherein the photoresist (2) is a positive novolac resin-based photoresist.

5. (currently amended) A photolithographic process a as claimed in claim 1, wherein the substrate (1a, 1b) is a master substrate for the production of a high density optical medium.

6. (original) A stamper (3) for the production of optical data storage media, manufactured by using the master substrate as used in claim 5.

7. (original) Use of a stamper (3) as claimed in claim 6 for the manufacture of a high density optical data storage medium.

8. (original) An optical data storage medium produced in an injection molding process by using the stamper (3) of claim 6.